IN THE CLAIMS

Current Listing of Claims:

1-14. (Canceled)

15. (Currently amended) The electroless plating structure according to claim 13,

An electroless plating structure on a copper pad, having a composition comprising:

 $pM_w sM_x B_y P_z$

wherein pM is a primary metal consisting of at least one element selected from the group consisting of Cu, Ag, and Au;

wherein sM is a secondary metal consisting of at least one element selected from the group consisting of Cr, Mo, W, Mn, Tc, and Re;

wherein B and P represent boron and phosphorus, respectively; and
wherein w has a range from about 0.5 to about 0.99, x has a range from 0.0 to
about 0.2, y has a range from about .01 to about 0.1, and z has a range from 0.0 to
about 0.02.

16. (Currently amended) The electroless plating structure according to claim 13,

An electroless plating structure on a copper pad, having a composition comprising:

 $\underline{pM_w}\underline{sM_x}\underline{B_y}\underline{P_z}$

wherein pM is a primary metal consisting of at least one element selected from the group consisting of Cu, Ag, Au, Pd, Pt, Ni, Rh, and Ir;

wherein sM is a secondary metal consisting of at least one element selected from the group consisting of Cr, Mo, W, Mn, Tc, and Re;

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wherein B and P represent boron and phosphorus, respectively; and wherein w has a range from about 0.5 to about 0.99, x has a range from a value approaching but not equal to 0.0 to about 0.02, y has a range from about .01 to about 0.1, and z has a range from 0.0 to about 0.02.

- 17. (Previously presented) The electroless plating structure according to claim 16, wherein pM is a primary metal consisting of at least one element selected from the group consisting of Ni, Pd, and Pt.
 - 18. (Canceled)
- 19. (Currently amended) The electroless plating structure according to claim 13,

 An electroless plating structure on a copper pad, having a composition comprising:

 $pM_w sM_x B_y P_z$

wherein pM is a primary metal consisting of at least one element selected from the group consisting of Rh and Ir;

wherein sM is a secondary metal consisting of at least one element selected from the group consisting of Cr, Mo, W, Mn, Tc, and Re;

wherein B and P represent boron and phosphorus, respectively; and
wherein w has a range from about 0.5 to about 0.99, x has a range from 0.0 to
about 0.2, y has a range from about .01 to about 0.1, and z has a range from 0.0 to
about 0.02.

20-31. (Canceled)

32. (Previously presented) An electroless plating structure on a copper pad, having a composition comprising:

 $pM_wsM_xB_yP_z\\$

wherein pM is a primary metal consisting of at least one element selected from the group consisting of Cu, Ag, Au, Pd, Pt, Ni, Rh, and Ir;

wherein sM is a secondary metal consisting of at least one element selected from the group consisting of Cr, Mo, W, Mn, Tc, and Re;

wherein B and P represent boron and phosphorus, respectively; and wherein w has a range from about 0.5 to about 0.99, x has a range from 0.0 to about 0.2, y has a range from about .01 to about 0.1, and z has a range from a value approaching but not equal to 0.0 to about 0.02.

- 33. (Previously presented) The electroless plating structure according to claim 32, wherein x has a range from a value approaching but not equal to 0.0 to about 0.02.
- 34. (Previously presented) The electroless plating structure according to claim 32, wherein pM is a primary metal consisting of at least one element selected from the group consisting of Rh and Ir.
- 35. (Previously presented) An electroless plating structure on a copper pad, having a composition comprising:

 $Co_w s M_x B_v P_z$

wherein sM is a secondary metal consisting of at least one element selected from the group consisting of Cr, Mo, W, Mn, Tc, and Re;

wherein Co, B, and P represent cobalt, boron, and phosphorus, respectively; and

wherein w has a range from about 0.5 to about 0.99, x has a range from 0.0 to about 0.2, y has a range from about .01 to about 0.1, and z has a range from a value approaching but not equal to 0.0 to about 0.02.

- 36. (Previously presented) The electroless plating structure of claim 35 wherein x has a range from a value approaching but not equal to 0.0 to about 0.02.
 - 37. (Canceled)

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